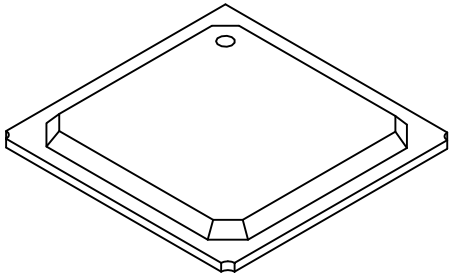
HMCCA,08/02/00,13:17:46,GPackage,Version: WMTBIG_APPROWL12 DARNO,10/09/01,13:48:43,OCLZ7Q

REVISION HISTORY							
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	DATABASE FILE NAME	GERBER FILE NAME	INCORPORATOR	DATE
00	C01446	INITIAL RELEASE	DARNO	N/A	N/A	DARNO	11/21/96
01	C01706	COPLANARITY WAS 8 MIL	DARNO	N/A	N/A	DARNO	03/29/97
02	C02166	ADDED 192/208 BALLS	GREME	N/A	N/A	GREME	10/10/97
03	C05151	ADDED NEW THICKNESS	MWALT	N/A	N/A	MWALT	12/11/98
04	C05516	CHANGED CAP TOLERANCE	MWALT	N/A	N/A	MWALT	03/16/99
05	C09754	CHANGED PBGA THICKNESS SCHEDULE	HMCCA	N/A	N/A	HMCCA	08/11/00
06	A51917	CORRECTED CORNER RADIUS	CHOIKS	N/A	N/A	CHOIKS	06/11/01
07	C13056	UPDATE TO JEDEC MS-034 AND ASME	DWACH	N/A	N/A	DARNO	08/03/01
VD	C13627	SUPERSEDED BY 82507	DARNO	N/A	N/A	DARNO	10/09/01



8. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.
   C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A, VARIATION AAF-1 EXCEPT FOR A1 AND b.

JEDEC(AMKOR) DIM	MIN	NOM	MAX
A1	0.40(0.30)	0.50(0.40)	0.60(0.50)
b	0.50(0.40)	0.60(0.50)	0.70(0.60)

7. A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK.
   AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 256.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 16 X 16.

2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL X.XX ±0.1 X.XX ±0.05 X.XXX ±0.030
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994
MATERIAL N/A
FINISH N/A
DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED RFUEN	09/17/96
CHECKED DARNO	09/17/96
PRODUCT MANAGER BGOGU	09/17/96
RELEASED Y.M. KANG	11/21/96

Amkor Technology, Inc. Chandler, Arizona, USA
Anam Semiconductor, Inc., Seoul, Korea
Amkor Technology Philippines, Inc. Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE - PBGA, 16 X 16 MATRIX, 17.00mm X 17.00mm, 15.00mm X 15.00mm X 0.80mm MOLD CAP, 1.00mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	71786	VD

STKP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	NONE	1 OF 4

FORM NO: MBPLAN1D1.DWG